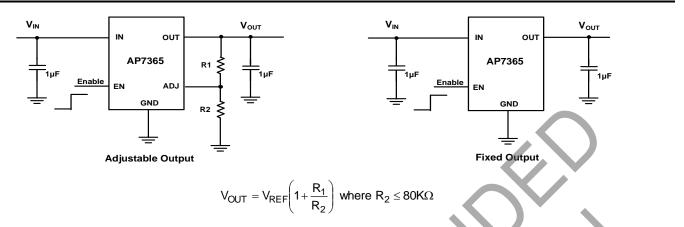


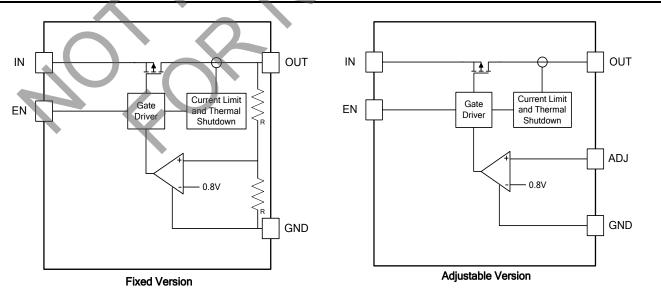
Typical Applications Circuit



Pin Descriptions

				Pin Num	ber			
Pin Name	SOT25 (Fixed)	SOT25 (ADJ)	U-DFN2020-6 (Fixed)	U-DFN2020-6 (ADJ)	SOT223	SOT89 (YR Package) SOT223 (ER Package)	SOT223 (EV Package)	Functions
IN	1	1	3	3	3	2	3	Voltage Input Pin. Bypass to ground through at least 1µF MLCC capacitor
GND	2	2	2	2	2	1	1	Ground
EN	3	3	1	1	—	—	— ·	Enable Input, Active High
ADJ	_	4	—	6		-		Output Feedback Pin
NC	4	_	5, 6	5			_	No Connection
OUT	5	5	4	4	1	3	2	Voltage Output Pin. Bypass to ground through 1µF MLCC capacitor

Functional Block Diagram





Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Ratings	Unit
ESD HBM	Human Body Model ESD Protection	2000	V
ESD MM	Machine Model ESD Protection	200	V
Vin	Input Voltage	6.5	V
_	OUT, EN Voltage	V _{IN} +0.3	V
—	Continuous Load Current per Channel	Internal Limited	_
T _{ST}	Storage Temperature Range	-65 to +150	°C
TJ	Maximum Junction Temperature	+150	°C

Recommended Operating Conditions (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Min	Max	Unit
Vin	Input Voltage	2	6	V
lout	Output Current (Note 4)	0	600	mA
T _A	Operating Ambient Temperature	-40	+85	°C

Note: 4. The device maintains a stable, regulated output voltage without a load current.

Electrical Characteristics (@TA = +25°C, VIN = VOUT +1V, COUT = 1µF, CIN = 1µF, VEN = 2V, unless otherwise specified.)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit	
V _{REF}	ADJ Reference Voltage (Adjustable Version)	Iout = 0mA	1	0.8	—	V	
IADJ	ADJ Leakage (Adjustable Version)		-	0.1	1.0	μA	
Vout	Output Voltage Accuracy	T _A = -40°C to +85°C, lout = 10% of lout-Max	-2	_	+2	%	
ΔVout /ΔVin/V	Line Regulation	$V_{IN} = (V_{OUT} + 1V)$ to V_{IN-Max} , $V_{EN} = V_{IN}$, $I_{OUT} = 1mA$	_	0.02	0.20	%/V	
∆Vout/Vout	Load Regulation	VIN = (VOUT +1V) to VIN-Max, IOUT = 1mA to 600mA	-1.0	_	+1.0	%	
		Vout < 2.5V, Iout = 600mA	_	370	600		
Vdropout	Dropout Voltage (Note 5)	V _{OUT} ≥ 2.5V, I _{OUT} = 600mA	_	300	400	mV	
lq	Input Quiescent Current	VEN = VIN, IOUT = 0mA	—	35	80	μA	
ISHDN	Input Shutdown Current	VEN = 0V, IOUT = 0mA	—	0.1	1.0	μA	
ILEAK	Input Leakage Current	$V_{EN} = 0V$, OUT grounded	—	0.1	1.0	μA	
ts⊤	Start-Up Time	V _{EN} = 0V to 2.0V in 1µs, Iout = 600mA	-	200	—	μs	
PSRR	PSRR (Note 6)	$V_{IN} = [V_{OUT} + 1V] V_{DC} + 0.5V_{ppAC},$ f = 1kHz, Iout = 50mA	_	65	_	dB	
Ishort	Short-Circuit Current	$V_{IN} = V_{IN-Min}$ to V_{IN-Max} , $V_{OUT} < 0.2V$ (fixed version) or 25% of V_{OUT} (ADJ version)	_	240	_	mA	
Ilimit	Current limit	VIN = VIN-Min to VIN-Max, Vout/Rout = 2.5A	0.8	1.4	—	А	
VIL	EN Input Logic Low Voltage	VIN = VIN-Min to VIN-Max	—	_	0.4	V	
Vін	EN Input Logic High Voltage	VIN = VIN-Min to VIN-Max	1.4		—	V	
len	EN Input Current	VIN = 0V or VIN-Max	-1	_	+1	μA	
TSHDN	Thermal Shutdown Threshold	—	—	+145	—	°C	
THYS	Thermal Shutdown Hysteresis	—	—	+15	—	°C	

Notes: 5. Dropout voltage is the voltage difference between the input and the output at which the output voltage drops 2% below its nominal value. This parameter only applies to input voltages above minimum $V_{IN} = 2.0V$.

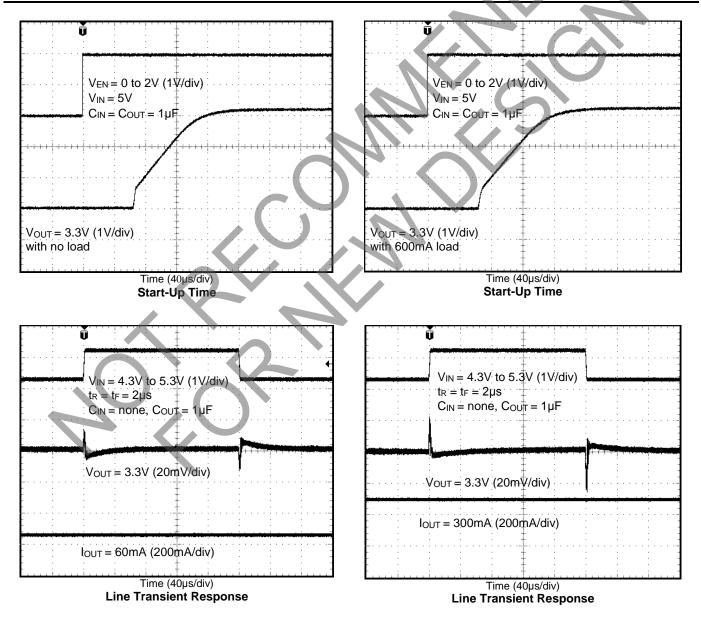
6. At V_{IN} < 2.3V, the PSRR performance may be reduced.



Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit	
	Thermal Resistance Junction-to-Ambient	SOT25 (Note 7)	_	169	_		
0		U-DFN2020-6 (Note 7)	_	132		0000	
θja		SOT89 (Note 7)	_	133		°C/W	
		SOT223 (Note 7)	_	142	_		
	Thermal Resistance Junction-to-Case	SOT25 (Note 7)	_	31	_		
0		U-DFN2020-6 (Note 7)	_	48	—	°C/W	
θις		SOT89 (Note 7)	—	30	-	-0/00	
		SOT223 (Note 7)	—	39			

Note: 7. Test condition for all packages: Device mounted on FR-4 substrate PC board, 1oz copper, with minimum recommended pad layout.

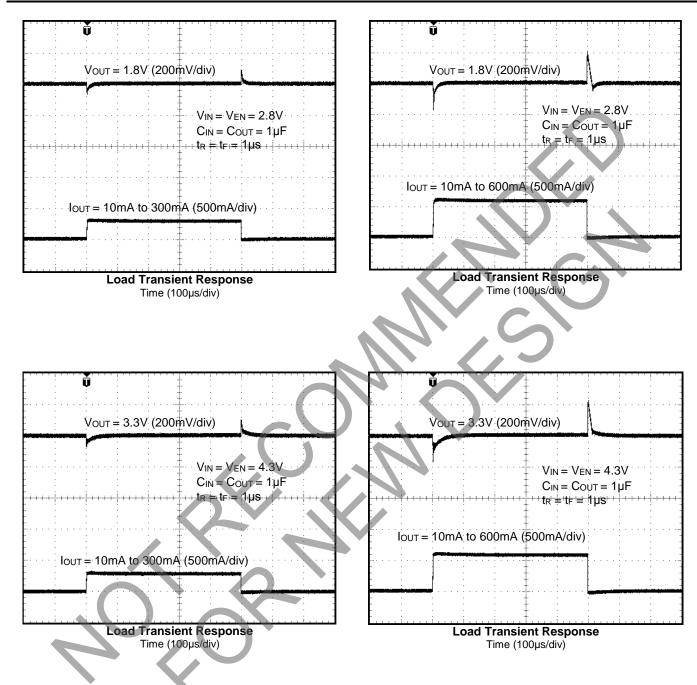
Typical Performance Characteristics



AP7365

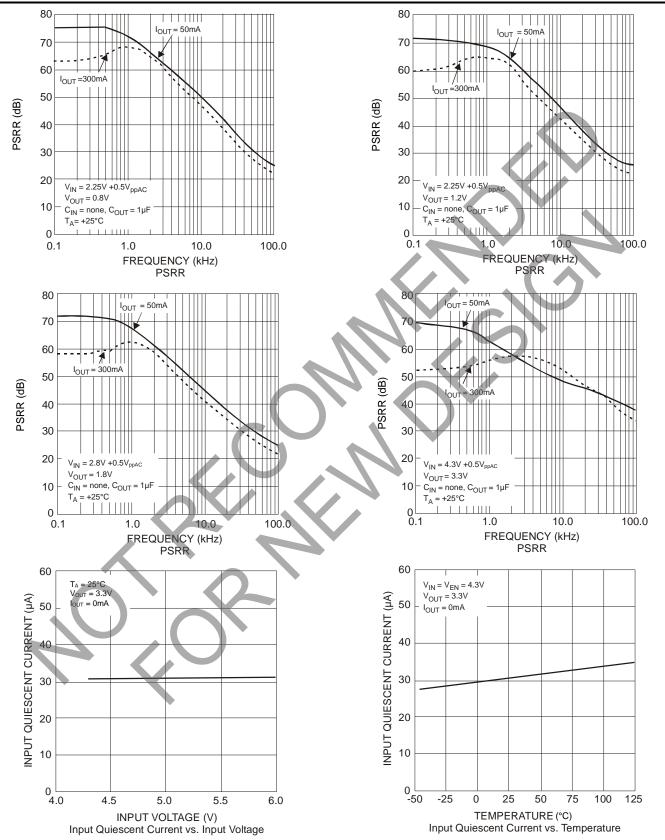


Typical Performance Characteristics (continued)





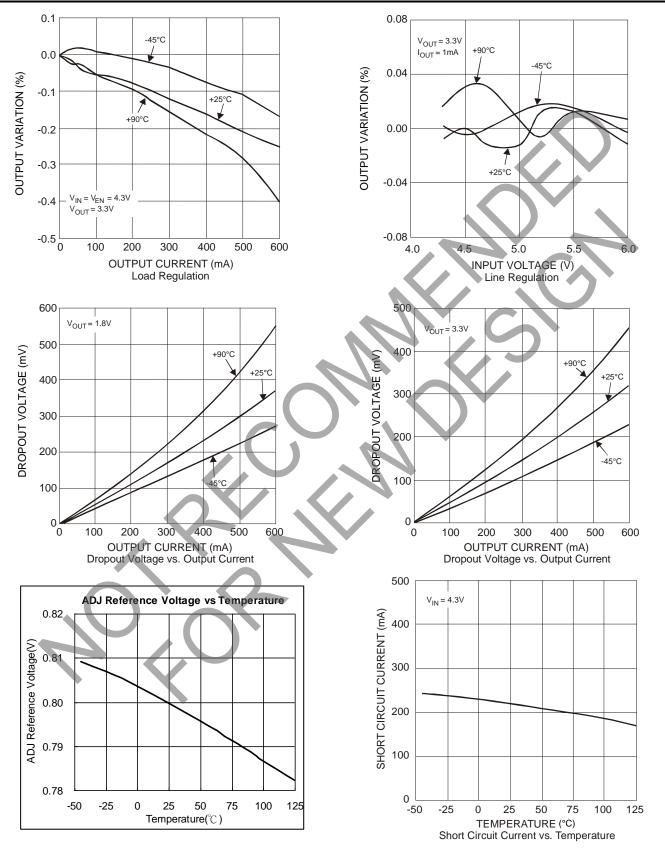
Typical Performance Characteristics (continued)



AP7365 Document number: DS32260 Rev. 11 - 3 Downloaded from Arrow.com.

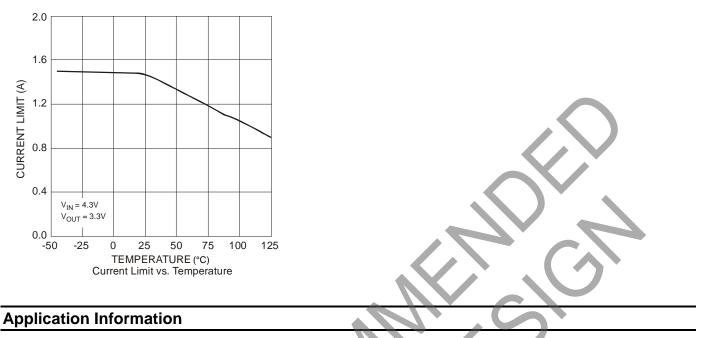


Typical Performance Characteristics (continued)





Typical Performance Characteristics (continued)

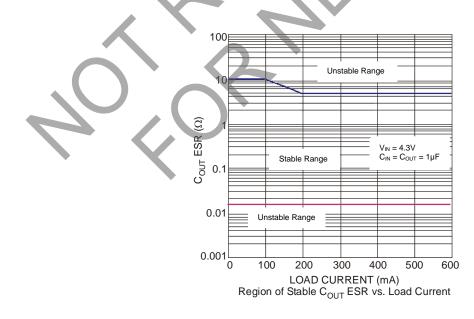


Input Capacitor

A 1µF ceramic capacitor is recommended between IN and GND pins to decouple input power supply glitch and noise. The amount of the capacitance may be increased without limit. This input capacitor must be located as close as possible to the device to assure input stability and reduce noise. For PCB layout, a wide copper trace is required for both IN and GND pins. A lower ESR capacitor type allows the use of less capacitance, while higher ESR type requires more capacitance.

Output Capacitor

The output capacitor is required to stabilize and improve the transient response of the LDO. The AP7365 is stable with very small ceramic output capacitors. Using a ceramic capacitor value that is at least 1μ F with ESR > $15m\Omega$ on the output ensures stability. Higher capacitance values help to improve line and load transient response. The output capacitance may be increased to keep low undershoot and overshoot. Output capacitor must be placed as close as possible to OUT and GND pins.

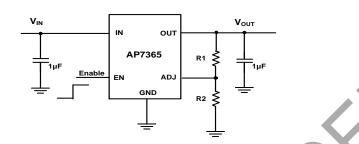




Application Information (continued)

Adjustable Operation

The AP7365 provides output voltage from 0.8V to 5.0V through external resistor divider as shown below.



The output voltage is calculated by:

$$V_{OUT} = V_{REF} \left(1 + \frac{R_1}{R_2} \right)$$

Where $V_{REF} = 0.8V$ (the internal reference voltage)

Rearranging the equation will give the following that is used for adjusting the output to a particular voltage:

$$R_1 = R_2 \left(\frac{V_{OUT}}{V_{REF}} - 1 \right)$$

To maintain the stability of the internal reference voltage, R2 needs to be kept smaller than 80kΩ.

No Load Stability

Other than external resistor divider, no minimum load is required to keep the device stable. The device will remain stable and regulated in no load condition.

ON/OFF Input Operation

The AP7365 is turned on by setting the EN pin high, and is turned off by pulling it low. If this feature is not used, the EN pin should be tied to IN pin to keep the regulator output on at all time. To ensure proper operation, the signal source used to drive the EN pin must be able to swing above and below the specified turn-on/off voltage thresholds listed in the Electrical Characteristics section under V_{IL} and V_{IH}.

Current Limit Protection

When output current at OUT pin is higher than current limit threshold, the current limit protection will be triggered and clamp the output current to approximately 1.4A to prevent overcurrent and to protect the regulator from damage due to overheating.

Short Circuit Protection

When OUT pin is short-circuit to GND, short circuit protection will be triggered and clamp the output current to approximately 240mA. This feature protects the regulator from overcurrent and damage due to overheating.

Thermal Shutdown Protection

Thermal protection disables the output when the junction temperature rises to approximately +145°C, allowing the device to cool down. When the junction temperature reduces to approximately +130°C, the output circuitry is enabled again. Depending on power dissipation, thermal resistance and ambient temperature, the thermal protection circuit may cycle on and off. This cycling limits the heat dissipation of the regulator, protecting it from damage due to overheating.

Ultra Fast Start-Up

After enabled, the AP7365 is able to provide full power in as little as hundreds of microseconds, typically 200µs, without sacrificing low ground current. This feature will help load circuitry move in and out of standby mode in real time, eventually extend battery life for mobile phones and other portable devices.

Downloaded from Arrow.com.



Application Information (continued)

Fast Transient Response

Fast transient response LDO can extend battery life. TDMA-based cell phone protocols such as Global System for Mobile Communications (GSM) have a transmit/receive duty factor of only 12.5%, enabling power savings by putting much of the baseband circuitry into standby mode in between transmit cycles. In baseband circuits, the load often transitions virtually instantaneously from 100µA to 100mA. To meet this load requirement, the LDO must react very quickly without a large voltage drop or overshoot — a requirement that cannot be met with conventional, general-purpose LDO.

The AP7365's fast transient response from 0 to 600mA provides stable voltage supply for fast DSP and GSM chipset with fast changing load.

Low Quiescent Current

The AP7365, consuming only around 35µA for all input ranges, provides great power saving in portable and low power applications.

Wide Output Range

The AP7365, with a wide output range of 0.8V to 5.0V, provides a versatile LDO solution for many portable applications.

Power Dissipation

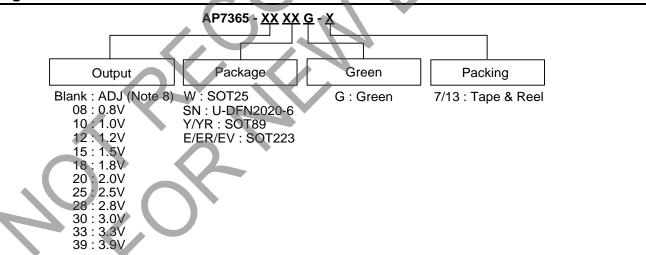
The device power dissipation and proper sizing of the thermal plane connected to the thermal pad is critical to avoid thermal shutdown and ensure reliable operation. Power dissipation of the device depends on input voltage and load conditions and can be calculated by:

PD = (VIN - VOUT) X IOUT

The maximum power dissipation, handled by the device, depends on the maximum junction to ambient thermal resistance, maximum ambient temperature, and maximum device junction temperature, which can be calculated by the equation in the following:

 $PD(MAX@T_A) = \frac{(+145^{\circ}C - T_A)}{R_{\theta JA}}$

Ordering Information



Part Number	Package Code Packaging —		7"/13" Tape and Reel		
Fart Nulliber	Fackage Code	Fackaging	Quantity	Part Number Suffix	
AP7365-XXWG-7	W	SOT25	3,000/Tape & Reel	-7	
AP7365-XXSNG-7	SN	U-DFN2020-6	3,000/Tape & Reel	-7	
AP7365-XXYG-13	Y	SOT89	2,500/Tape & Reel	-13	
AP7365-XXYRG-13	YR	SOT89	2,500/Tape & Reel	-13	
AP7365-XXEG-13	E	SOT223	2,500/Tape & Reel	-13	
AP7365-XXERG-13	ER	SOT223	2,500/Tape & Reel	-13	
AP7365-XXEVG-13	EV	SOT223	2,500/Tape & Reel	-13	

Note: 8. Adjustable version is only available in SOT25 and U-DFN2020-6 packages.



Marking Information

(1) SOT25

(Top V 5 XX Y 1 2	▲ <u>XX</u> : Identificatio <u>Y</u> : Year 0~9 <u>W</u> : Week : A~ a~z : 27~5 52 and 53	Z : 1~26 week; 52 week; z represents week	
Part Number	Package	Identification Code	
AP7365-WG-7	SOT25	VA	
AP7365-08WG-7	SOT25	VB	
AP7365-10WG-7	SOT25	VC	
AP7365-12WG-7	SOT25	VD	
AP7365-15WG-7	SOT25	VE	
AP7365-18WG-7	SOT25	VF	
AP7365-20WG-7	SOT25	VG	
AP7365-25WG-7	SOT25	VH	
AP7365-28WG-7	SOT25	VJ	
AP7365-30WG-7	SOT25	VK	
AP7365-33WG-7	SOT25	VM	*
AP7365-39WG-7	SOT25	VN	

(2) U-DFN2020-6

	(Top Viev	XX : Identification \underline{Y} : Year : 0-9 W : Week : A-Z :	1~26 week; week; z represents eek
	Part Number	Package	Identification Code
	AP7365-SNG-7	U-DFN2020-6	VA
	AP7365-08SNG-7	U-DFN2020-6	VB
	AP7365-10SNG-7	U-DFN2020-6	VC
	AP7365-12SNG-7	U-DFN2020-6	VD
	AP7365-15SNG-7	U-DFN2020-6	VE
	AP7365-18SNG-7	U-DFN2020-6	VF
	AP7365-20SNG-7	U-DFN2020-6	VG
	AP7365-25SNG-7	U-DFN2020-6	VH
	AP7365-28SNG-7	U-DFN2020-6	VJ
	AP7365-30SNG-7	U-DFN2020-6	VK
•	AP7365-33SNG-7	U-DFN2020-6	VM

AP7365-39SNG-7

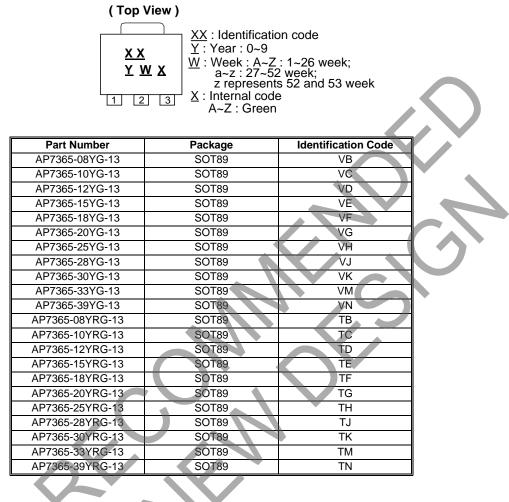
U-DFN2020-6

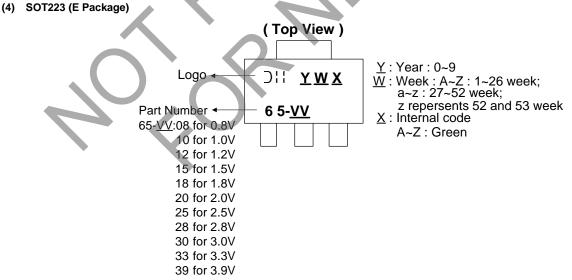
VN



Marking Information (continued)

(3) SOT89

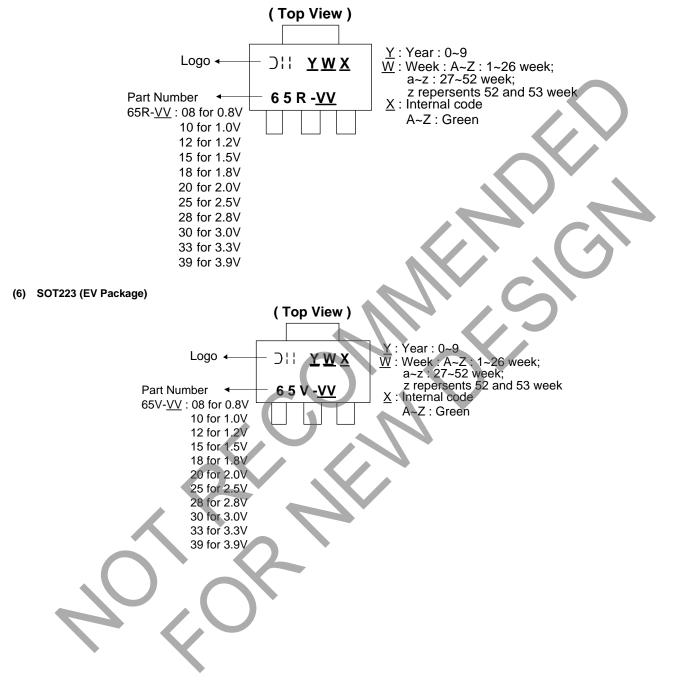






Marking Information (continued)

(5) SOT223 (ER Package)

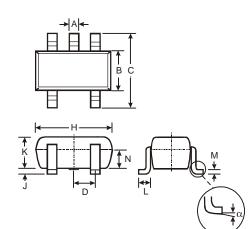




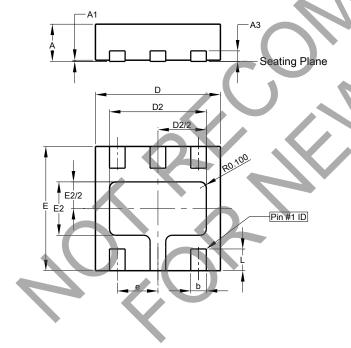
Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

(1) Package Type: SOT25



(2) Package Type: U-DFN2020-6



	U-DFN	2020-6	
Dim	Min	Max	Тур
Α	0.57	0.63	0.60
A1	0	0.05	0.03
A3	-	-	0.15
b	0.20	0.30	0.25
D	1.95	2.075	2.00
D2	1.45	1.65	1.55
е	-	-	0.65
Е	1.95	2.075	2.00
E2	0.76	0.96	0.86
L	0.30	0.40	0.35
	Dimens	ions in	mm

SOT25

0.35

1.50

2.70

2.90

0.35

0.10

0.70

0°

0.013 0.10

1.00 1.30

All Dimensions in mm

Min Max Typ

0.50

1.70

3.00

3.10

0.55

8°

0.20 0.15

0.80 0.75

0.38

1.60

2.80

0.95

3.00

0.05

1.10

0.40

Dim

Α

В

С

D

Н

J

Κ

L

M

Ń

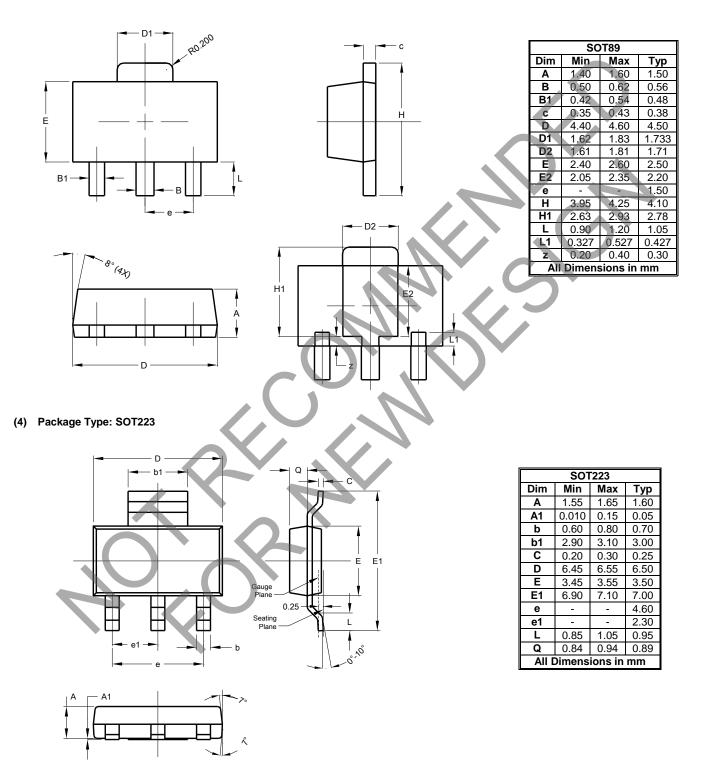
α



Package Outline Dimensions (continued)

Please see http://www.diodes.com/package-outlines.html for the latest version.

(3) Package Type: SOT89

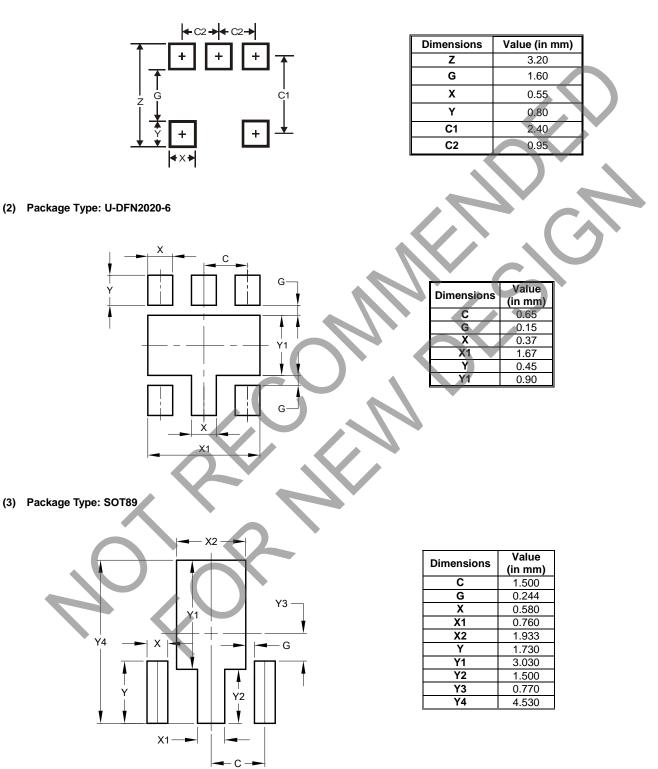




Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

(1) Package Type: SOT25

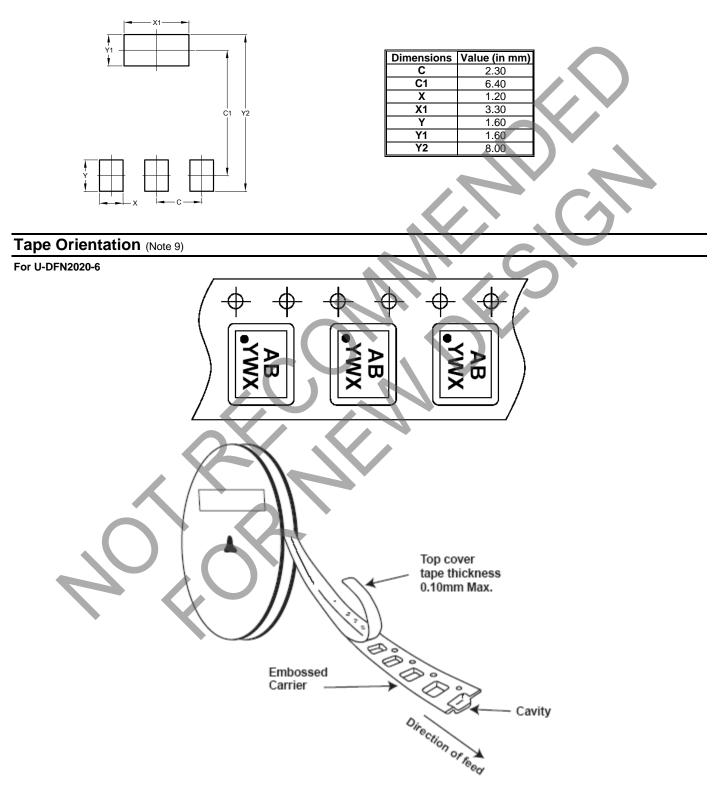




Suggested Pad Layout (continued)

Please see http://www.diodes.com/package-outlines.html for the latest version.

(4) Package Type: SOT223



Note: 9. The taping orientation of the other package type can be found on our website at https://www.diodes.com/assets/Packaging-Support-Docs/ap02007.pdf



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